A ROBUST DEVICE CARRIER FOR FORMING A SEMICONDUCTOR PACKAGE

Abstract

A device carrier for packaging a semiconductor device. The device carrier comprises a device substrate and a stiffener structure. The device substrate couples the semiconductor device comprising a plurality of contacts thereto. The device substrate comprises a plurality of traces for coupling with the plurality of contacts of the semiconductor device, the plurality of traces defining an array segment in the device substrate and circumscribed by the periphery of the array segment. The stiffener structure is formed on the device substrate and disposed away from the array segment. The stiffener structure is shaped and dimensioned for impeding flexure to the array segment of the device substrate.

Figure 1